

## Wi-Fi 6E with BLUETOOTH 5.4 FOR NEXT GENERATION INDUSTRIAL IOT



Introducing the first of the Sona<sup>TM</sup> Wi-Fi 6/6E product line from Laird Connectivity, the IF573, based upon Infineon's leading AIROC<sup>TM</sup> CYW55573 chipset. A truly robust industrial IoT module: one that's rugged, small, globally certified, has reliable connectivity, and is easy to integrate.

Our new Sona<sup>TM</sup> IF573 answers the call for next-gen wireless IoT. The Sona<sup>TM</sup> IF573 is purpose-built for industrial IoT connectivity with access to both PCIe and SDIO interfaces, industrial operating temp range, latest generation Wi-Fi and BT combined with both pluggable card and SMT M.2 packaging.

When matched with our industry leading services and support, the Sona IF573 is the only Wi-Fi module of its kind, addressing all your Wi-Fi 6E needs.

**Compatible:** Our **Linux Backports** package supports many Linux kernels including v6.1.x.

**Reliable:** Integrated PA (Power Amplifier) and LNA (Low Noise Amplifier) with **2x2 MU-MIMO** antenna for reliable connectivity in harsh RF environments.

**Robust:** Rich feature-set including 802.11ax Wi-Fi 6E and Dual-Mode BT v5.4. Support for the 6GHz spectrum. Reliable **industrial temperature range**, and solder-down module is suitable for industrial rugged applications.

**Secure:** Supports the latest WPA3 security standards.

- Antenna: 2x2 **Wi-Fi 6E** (802.11ax), x1 **Bluetooth 5.4**
- Support for 2.4, 5 and 6GHz (UNII-1 – 3 & UNII-5 – 8)
- 802.11ax STA mode and Soft AP mode
- **Bluetooth 5.4** Bluetooth Low Energy (BLE)
- Integrated **Wi-Fi + Bluetooth coexistence** for seamless connectivity
- High Speed host interface:
  - Mode 1: PCIe 3.0 (Wi-Fi) and UART (BT)
  - Mode 2: SDIO 3.0 (Wi-Fi) and UART (BT)
- Industrial Temperature Rating (-40° to +85 °C)
- **Ultra-small footprint** (13 mm x 18 mm) including on-board antenna MHF connectors
- Module options:
  - RF Antenna pin
  - On-board MHF4 connector
  - M.2 2230 Key E Plug-in module
  - M.2 1318 SMT module
- **Rugged Design** – solder down form factor
- **Global Certifications** – FCC, IC, CE, MIC, RCM, BT SIG
- **Linux Backports** for broad kernel support. Includes Android 12/13 support.

## FEATURES AT A GLANCE



**TRI-BAND WI-FI 6 (6GHZ SPECTRUM SUPPORT)**  
2.4/5/6 GHz spectrum availability for flexibility and higher performance.



**RELIABLE CONNECTIVITY**  
802.11ax Wi-Fi with integrated PA and LNA combined add up to a reliable module for harsh RF conditions.



**SOFTWARE FLEXIBILITY AND SPEED TO MARKET**  
Open-Source software and Linux Backports ensures compatibility with a wide variety of Linux kernels and latest security standards.



**INDUSTRIAL OPERATING RANGE**  
Designed to the industrial temperature range of -40°C to +85°C for every component utilized.



**GLOBAL APPROVALS**  
Carries worldwide FCC, IC, CE, RCM, MIC and Bluetooth SIG approvals.



## APPLICATION AREAS



Medical Devices (Infusion pumps, HD Imaging, Vitals Monitoring, Gateways, Beds, blood analyzers)



Industrial IoT Connectivity



Rugged Handheld Devices

## KEY SPECIFICATIONS

CATEGORY	FEATURE	SPECIFICATION
Wireless Specification	Wi-Fi	Wi-Fi 6E (802.11 a/b/g/n/ac/ax)
	Bluetooth®	v5.4 (BDR + EDR + BLE)
	Frequency	Tri-Band 2.4 GHz & 5 GHz & 6 GHz (Up to 7.125 GHz)
	Transmit Power	+ 18 dBm (maximum)
	Antenna Options	On-board MHF4 connector(s), trace pin for external antennas Separate Wi-Fi and BT antenna RF connections
	Raw Data Rates (PHY)	2.4 GHz: Up to 574 Mbps, 1024-QAM, 2x2 MIMO 5 GHz/6 GHz: Up to 1.2 Gbps, 1024-QAM, 2x2 MIMO
Key Wi-Fi Features	Wi-Fi 6E (802.11ax)	<ul style="list-style-type: none"> <li>20, 40, and 80MHz wide channels, 1024 QAM</li> <li>Integrated PA/LNA</li> <li>On-board x3 MHF4 connectors</li> <li>Supports OFDMA, TWT, Virtual Simultaneous Dual Band, Zero Wait DFS, BSS Coloring</li> </ul> 802.11d/h/k/r/v/w/ai
Host Interface and Peripherals	Network Interfaces	PCIe v3.0 Gen 2 (Wi-Fi) and HCI using HS-UART (BT) SDIO 3.0 (Wi-Fi) and HCI using HS-UART (BT)
Key Bluetooth Features	Bluetooth Low Energy	<ul style="list-style-type: none"> <li>BDR + EDR + BLE</li> <li>LE 2 Mbps PHY</li> <li>LE Long Range (LE-LR)</li> <li>Adaptive frequency hopping (AFH)</li> <li>Quality of service (QoS)</li> <li>Secure simple pairing (SSP)</li> <li>UART baud rates up to 4 Mbps</li> <li>Fast connect (interlaced page and inquiry scans)</li> <li>Dedicated BT path with MHF4 connector or trace pin</li> </ul>
Supply Voltage		3.3VDC (Supply) and 1.8VDC (I/O)
Physical	Dimensions	13 mm x 18 mm x 0.43 mm (M.2 1318 SMT Module) 22 mm x 30 mm x 3.1 mm (M.2 E-Key Module)
Environmental	Operating Temp Range	-40°C to +85°C
Miscellaneous	Lead Free	Lead-free and RoHS-compliant
	Development Kit	Development board, accessories, and evaluation software
Regulatory	Approvals	FCC/IC/CE/MIC/RCM (Pending)
Qualifications	Bluetooth SIG	Bluetooth SIG Approval

**For full specifications on the Sona IF573 modules, please see the appropriate datasheet.**

PART #	DESCRIPTION
453-00117R	Module, Sona IF573, MIMO, M.2 1318, MHF4, Tape and Reel
453-00117C	Module, Sona IF573, MIMO, M.2 1318, MHF4, Cut Tape
453-00118R	Module, Sona IF573, MIMO, M.2 1318, Trace Pin, Tape and Reel
453-00118C	Module, Sona IF573, MIMO, M.2 1318, Trace Pin, Cut Tape
453-00119	Module, Sona IF573, MIMO, M.2 2230, Key E, SDIO, UART
453-00120	Module, Sona IF573, MIMO, M.2 2230, Key E, PCIe, UART
453-00119-K1	Development Kit, Sona IF573, MIMO, M.2, Key E, SDIO, UART
453-00120-K1	Development Kit, Sona IF573, MIMO, M.2, Key E, PCIe, UART